

## CDx4HC243、CDx4HCT243 具有三态输出的高速 CMOS 逻辑四路总线收发器

### 1 特性

- 当  $V_{CC} = 5V$ 、 $C_L = 15pF$ 、 $T_A = 25^\circ C$  时，传播延迟典型值 (A 到 B, B 到 A) 为 7ns
- 三态输出
- 缓冲输入
- 扇出 (在温度范围内)
  - 标准输出：10 个 LSTTL 负载
  - 总线驱动器输出：15 个 LSTTL 负载
- 宽工作温度范围：-55°C 至 125°C
- 平衡的传播延迟及转换时间
- 与 LSTTL 逻辑 IC 相比，功耗显著降低
- HC 类型
  - 2 V 至 6 V 工作电压
  - 高抗噪性：当  $V_{CC} = 5V$  时， $N_{IL} = 30\%$ ， $N_{IH} = V_{CC}$  的 30%
- HCT 类型
  - 工作电压为 4.5 V 至 5.5 V
  - 直接 LSTTL 输入逻辑兼容性， $V_{IL} = 0.8V$  (最大值)， $V_{IH} = 2V$  (最小值)
  - CMOS 输入兼容性，当电压为  $V_{OL}$ 、 $V_{OH}$  时， $I_i \leq 1\mu A$

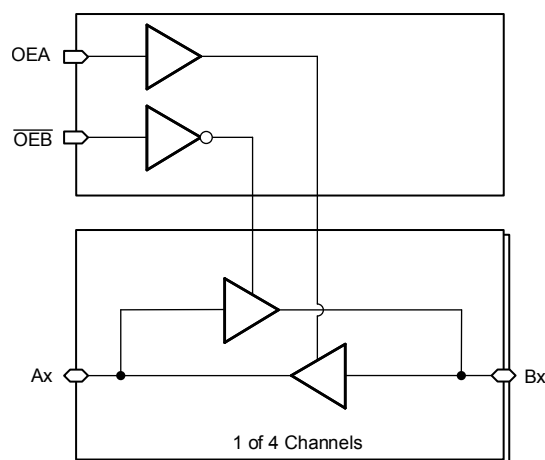
### 2 说明

CDx4HC243 和 CDx4HCT243 是具有三态输出的四路总线收发器。OEA 和  $\overline{OEB}$  输入可通过器件来控制高阻抗状态和通信方向。

器件信息

器件型号	封装 <sup>(1)</sup>	封装尺寸 (标称值)
CD54HC243F	CDIP (14)	19.55mm × 6.71mm
CD74HC243E	PDIP (14)	19.31mm × 6.35mm
CD74HC243M	SOIC (14)	8.65mm × 3.90mm
CD74HCT243E	PDIP (14)	19.31mm × 6.35mm
CD74HCT243M	SOIC (14)	8.65mm × 3.90mm

(1) 如需了解所有封装，请参阅数据表末尾的可订购产品附录。



功能方框图



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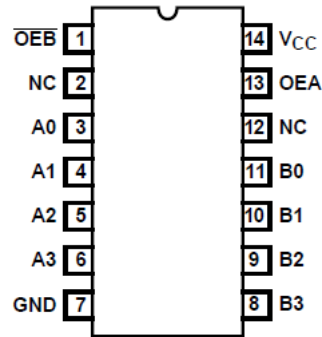
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### 3 Revision History

注：以前版本的页码可能与当前版本的页码不同

<b>Changes from Revision D (October 2003) to Revision E (March 2022)</b>	<b>Page</b>
• 更新了整个文档中的编号、格式、表格、图和交叉参考，以反映现代数据表标准.....	1

## 4 Pin Configuration and Functions



**J, N, or D Package**  
**14-Pin CDIP, PDIP, or SOIC**  
**Top View**

## 5 Specifications

### 5.1 Absolute Maximum Ratings

Over operating free-air temperature range (unless otherwise noted)<sup>(1)</sup>

		MIN	MAX	UNIT
$V_{CC}$	Supply voltage	-0.5	7	V
$I_{IK}$	Input diode current	For $V_I < -0.5V$ or $V_O > V_{CC} + 0.5V$		$\pm 20$ mA
$I_{OK}$	Output diode current	For $V_C < -0.5V$ or $V_O > V_{CC} + 0.5V$		$\pm 20$ mA
$I_O$	Drian Current, per output	For $-0.5V < V_O < V_{CC} + 0.5V$		$\pm 35$ mA
$I_O$	Output source or sink current per output pin	For $V_O > -0.5V$ or $V_O < V_{CC} + 0.5V$		$\pm 25$ mA
	Continuous current through $V_{CC}$ or GND		$\pm 70$	mA
$T_{stg}$	Storage temperature range	-65	150	°C
$T_J$	Junction temperature		150	°C
	Lead temperature (Soldering 10s)(SOIC - Lead Tips Only)		300	°C

- (1) Stresses beyond those listed under *absolute maximum ratings* may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions beyond those indicated under *recommended operating conditions* is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

### 5.2 Recommended Operating Conditions

		MIN	MAX	UNIT	
$V_{CC}$	Supply voltage range	HC Types	2	6	V
		HCT Types	4.5	5.5	
$V_I$	Input voltage	0	$V_{CC}$	V	
$V_O$	Output voltage	0	$V_{CC}$	V	
$t_t$	Input rise and fall time	$V_{CC} = 2V$		1000	ns
		$V_{CC} = 4.5V$		500	
		$V_{CC} = 6V$		400	
$T_A$	Temperature Range	-55	125	°C	

### 5.3 Thermal Information

THERMAL METRIC		N (PDIP)	D (SOIC)	UNIT
		14 PINS	14 PINS	
$R_{\theta JA}$	Junction-to-ambient thermal resistance <sup>(1)</sup>	80	86	°C/W

- (1) For more information about traditional and new thermal metrics, see the [Semiconductor and IC Package Thermal Metrics](#) application report.

## 5.4 Electrical Characteristics

PARAMETER		TEST CONDITIONS <sup>(1)</sup>	V <sub>CC</sub> (V)	25°C			-40°C to 85°C		-55°C to 125°C		UNIT
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
<b>HC TYPES</b>											
V <sub>IH</sub>	High-level input voltage		2	1.5			1.5		1.5		V
			4.5	3.15			3.15		3.15		
			6	4.2			4.2		4.2		
V <sub>IL</sub>	Low-level input voltage		2		0.5		0.5		0.5		V
			4.5		1.35		1.35		1.35		
			6		1.8		1.8		1.8		
V <sub>OH</sub>	High-level output voltage CMOS loads	I <sub>OH</sub> = - 20 μA	2	1.9			1.9		1.9		V
		I <sub>OH</sub> = - 20 μA	4.5	4.4			4.4		4.4		
		I <sub>OH</sub> = - 20 μA	6	5.9			5.9		5.9		
	High-level output voltage TTL loads	I <sub>OH</sub> = - 6mA	4.5	3.98			3.84		3.7		
		I <sub>OH</sub> = - 7.8mA	6	5.48			5.34		5.2		
V <sub>OL</sub>	Low-level output voltage CMOS loads	I <sub>OL</sub> = 20 μA	2		0.1		0.1		0.1		V
		I <sub>OL</sub> = 20 μA	4.5		0.1		0.1		0.1		
		I <sub>OL</sub> = 20 μA	6		0.1		0.1		0.1		
	Low-level output voltage TTL	I <sub>OL</sub> = 6mA	4.5		0.26		0.33		0.4		
		I <sub>OL</sub> = 7.8mA	6		0.26		0.33		0.4		
I <sub>I</sub>	Input leakage current	V <sub>CC</sub> or GND	6		±0.1		±1		±1	μA	
I <sub>CC</sub>	Supply Current	V <sub>CC</sub> or GND	6		8		80		160	μA	
I <sub>OZ</sub>	Three-state leakage current	V <sub>IL</sub> or V <sub>IH</sub>	6		±0.5		±0.5		±10	μA	
<b>HCT TYPES</b>											
V <sub>IH</sub>	High-level input voltage		4.5 to 5.5	2			2		2		V
V <sub>IL</sub>	Low-level input voltage		4.5 to 5.5		0.8		0.8		0.8		V
V <sub>OH</sub>	High-level output voltage CMOS loads	I <sub>OH</sub> = - 20 μA	4.5	4.4			4.4		4.4		V
	High-level output voltage TTL loads	I <sub>OH</sub> = - 6mA	4.5	3.98			3.84		3.7		
V <sub>OL</sub>	Low-level output voltage CMOS loads	I <sub>OL</sub> = 20 μA	4.5		0.1		0.1		0.1		V
	Low-level output voltage TTL loads	I <sub>OL</sub> = 6mA	4.5		0.26		0.33		0.4		
I <sub>I</sub>	Input leakage current	V <sub>CC</sub> to GND	5.5		±0.1		±1		±1	μA	
I <sub>CC</sub>	Supply current	V <sub>CC</sub> or GND	5.5		8		80		160	μA	
ΔI <sub>CC</sub> <sup>(2)</sup> <sup>(3)</sup>	Additional supply current per input pin	One of An or Bn	4.5 to 5.5	100	396		495		539		μA
		One of OEA or OEB	4.5 to 5.5	100	216		270		294		
I <sub>OZ</sub>	Three-state leakage current	V <sub>IL</sub> or V <sub>IH</sub>	5.5		±0.5		±5		±10	μA	

(1) V<sub>I</sub> = V<sub>IH</sub> or V<sub>IL</sub>, unless otherwise noted.

(2) For dual-supply systems theoretical worst case (V<sub>I</sub> = 2.4 V, V<sub>CC</sub> = 5.5 V) specification is 1.8 mA.

(3) Inputs held at V<sub>CC</sub> - 2.1.

## 5.5 Switching Characteristics

Input  $t_i = 6\text{ns}$ . Unless otherwise specified,  $C_L = 50\text{pF}$

PARAMETER		$V_{CC}$ (V)	25°C		-40°C to 85°C	-55°C to 125°C	UNIT
			TYP	MAX	MAX	MAX	
<b>HC TYPES</b>							
$t_{pd}$	Propagation delay data to outputs	2		90	115	135	ns
		4.5	7 <sup>(1)</sup>	18	23	27	
		6		15	20	23	
$t_{PZL}, t_{PZH}$	Output high-Z, to high level to low level	2		150	190	225	ns
		4.5	12 <sup>(1)</sup>	30	38	45	
		6		26	33	38	
$t_{PHZ}, t_{PLZ}$	Output high level, output low level to high-Z	2		150	190	225	ns
		4.5	12 <sup>(1)</sup>	30	38	45	
		6		26	33	38	
$t_t$	Output transition times	2		60	75	90	ns
		4.5		12	15	18	
		6		10	13	15	
$C_i$	Input capacitance			10	10	10	pF
$C_O$	Three-state output capacitance			20	20	20	pF
$C_{pd}$ <sup>(2) (3)</sup>	Power dissipation capacitance	5	80				pF
<b>HCT TYPES</b>							
$t_{pd}$	Propagation delay data to outputs	4.5	9 <sup>(1)</sup>	22	28	33	ns
$t_{PZH}, t_{PLZ}$	Output high-Z to high level to low level	4.5	14 <sup>(1)</sup>	34	43	51	ns
$t_{PHZ}, t_{PLZ}$	Output high level, output low level to high-Z	4.5	14 <sup>(1)</sup>	35	44	53	ns
$t_t$	Output transition times	4.5		12	15	18	ns
$C_i$	Input capacitance			10	10	10	pF
$C_O$	Three-state output capacitance			20	20	20	pF
$C_{pd}$ <sup>(2) (3)</sup>	Power dissipation capacitance	5	91				pF

(1) Typical value tested at 5V,  $C_L = 15\text{pF}$ .

(2)  $C_{PD}$  is used to determine the dynamic power consumption, per channel.

(3)  $P_D = V_{CC}^2 f_i (C_{PD} + C_L)$  where  $f_i$  = Input Frequency,  $f_O$  = Output Frequency,  $C_L$  = Output Load Capacitance,  $V_{CC}$  = Supply Voltage.

## 6 Parameter Measurement Information

$t_{PD}$  is the maximum between  $t_{PLH}$  and  $t_{PHL}$

$t_t$  is the maximum between  $t_{TLH}$  and  $t_{THL}$

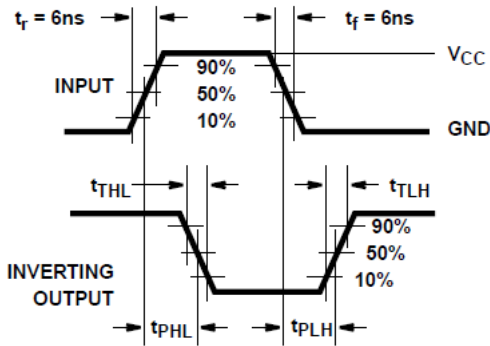


图 6-1. HC and HCT transition times and propagation delay times, combination logic

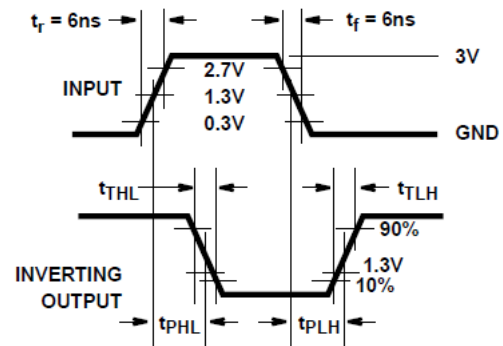


图 6-2. HCT transition times and propagation delay times, combination logic

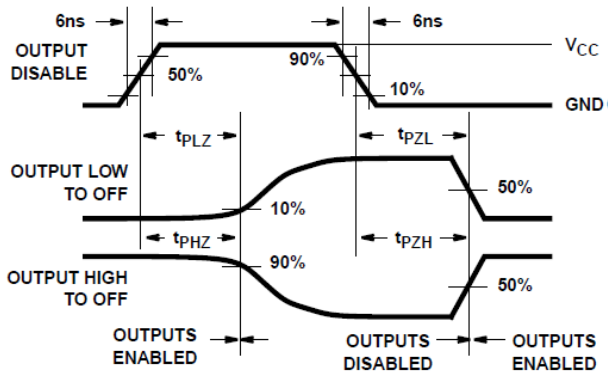


图 6-3. HC three-state propagation delay waveform

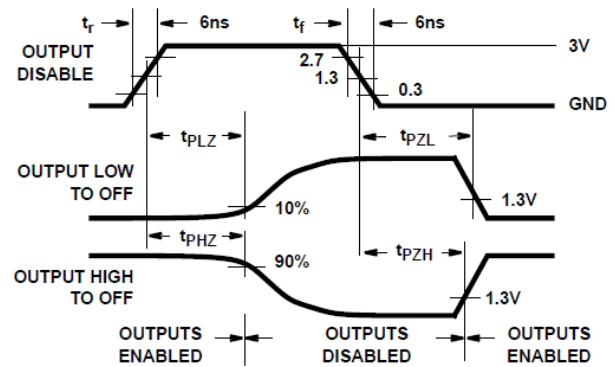
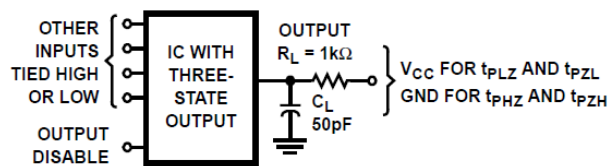


图 6-4. HCT three-state propagation delay waveform



NOTE: Open drain waveforms  $t_{PLZ}$  and  $t_{PZL}$  are the same as those for three-state shown on the left. The test circuit is Output  $R_L = 1k\Omega$  to  $V_{CC}$ ,  $C_L = 50pF$ .

图 6-5. HC and HCT three-state propagation delay test circuit

## 7 Detailed Description

### 7.1 Overview

The CDx4HC243 and CDx4HCT243 silicon-gate CMOS three-state bidirectional noninverting buffers are intended for two-way asynchronous communication between data buses. They have high-drive-current outputs that enable high-speed operation when driving large bus capacitances. These circuits possess the low power dissipation of CMOS circuits and have speeds comparable to low-power Schottky TTL circuits. They can drive 15 LSTTL loads.

The states of the output-enable ( $\overline{\text{OEB}}$ , OEA) inputs determine both the direction of flow (A to B, B to A), and the three-state mode.

### 7.2 Functional Block Diagram

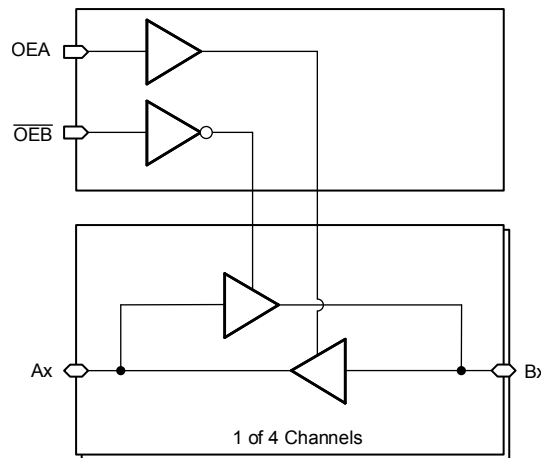


图 7-1. Functional Diagram

### 7.3 Device Functional Modes

表 7-1. Truth Table<sup>(1)(2)</sup>

Control Inputs		HC, HCT243 Series	
		Data port status	
OEB	OEA	An	Bn
H	H	O	I
L	H	Z	Z
H	L	Z	Z
L	L	I	O

- (1) H = High voltage level. L = Low voltage level. I = Input. O = Output (Same level as input). Z = High Impedance
- (2) To prevent excess currents in the High Z modes all I/O terminals should be terminated with 10kΩ to 1MΩ resistors.

## 8 Power Supply Recommendations

The power supply can be any voltage between the minimum and maximum supply voltage rating located in the *Recommended Operating Conditions*. Each  $V_{CC}$  terminal should have a good bypass capacitor to prevent power disturbance. A 0.1- $\mu$ F capacitor is recommended for this device. It is acceptable to parallel multiple bypass caps to reject different frequencies of noise. The 0.1- $\mu$ F and 1- $\mu$ F capacitors are commonly used in parallel. The bypass capacitor should be installed as close to the power terminal as possible for best results.

## 9 Layout

### 9.1 Layout Guidelines

When using multiple-input and multiple-channel logic devices inputs must not ever be left floating. In many cases, functions or parts of functions of digital logic devices are unused; for example, when only two inputs of a triple-input AND gate are used or only 3 of the 4 buffer gates are used. Such unused input pins must not be left unconnected because the undefined voltages at the outside connections result in undefined operational states. All unused inputs of digital logic devices must be connected to a logic high or logic low voltage, as defined by the input voltage specifications, to prevent them from floating. The logic level that must be applied to any particular unused input depends on the function of the device. Generally, the inputs are tied to GND or  $V_{CC}$ , whichever makes more sense for the logic function or is more convenient.

## 10 Device and Documentation Support

TI offers an extensive line of development tools. Tools and software to evaluate the performance of the device, generate code, and develop solutions are listed below.

### 10.1 Documentation Support

#### 10.1.1 Related Documentation

### 10.2 接收文档更新通知

要接收文档更新通知，请导航至 [ti.com](http://ti.com) 上的器件产品文件夹。点击 [订阅更新](#) 进行注册，即可每周接收产品信息更改摘要。有关更改的详细信息，请查看任何已修订文档中包含的修订历史记录。

### 10.3 支持资源

TI E2E™ [支持论坛](#) 是工程师的重要参考资料，可直接从专家获得快速、经过验证的解答和设计帮助。搜索现有解答或提出自己的问题可获得所需的快速设计帮助。

链接的内容由各个贡献者“按原样”提供。这些内容并不构成 TI 技术规范，并且不一定反映 TI 的观点；请参阅 TI 的 [《使用条款》](#)。

### 10.4 Trademarks

TI E2E™ is a trademark of Texas Instruments.

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### 10.5 Electrostatic Discharge Caution



This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

### 10.6 Glossary

[TI Glossary](#) This glossary lists and explains terms, acronyms, and definitions.

## 11 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

## 重要声明和免责声明

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**PACKAGING INFORMATION**

Orderable part number	Status (1)	Material type (2)	Package   Pins	Package qty   Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
<a href="#">8409001CA</a>	Active	Production	CDIP (J)   14	25   TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	8409001CA CD54HC243F3A
<a href="#">CD54HC243F</a>	Active	Production	CDIP (J)   14	25   TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	CD54HC243F
CD54HC243F.A	Active	Production	CDIP (J)   14	25   TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	CD54HC243F
<a href="#">CD54HC243F3A</a>	Active	Production	CDIP (J)   14	25   TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	8409001CA CD54HC243F3A
CD54HC243F3A.A	Active	Production	CDIP (J)   14	25   TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	8409001CA CD54HC243F3A
<a href="#">CD74HC243E</a>	Active	Production	PDIP (N)   14	25   TUBE	Yes	NIPDAU	N/A for Pkg Type	-55 to 125	CD74HC243E
CD74HC243E.A	Active	Production	PDIP (N)   14	25   TUBE	Yes	NIPDAU	N/A for Pkg Type	-55 to 125	CD74HC243E
CD74HC243EE4	Active	Production	PDIP (N)   14	25   TUBE	Yes	NIPDAU	N/A for Pkg Type	-55 to 125	CD74HC243E
<a href="#">CD74HC243M</a>	Obsolete	Production	SOIC (D)   14	-	-	Call TI	Call TI	-55 to 125	HC243M
<a href="#">CD74HC243M96</a>	Active	Production	SOIC (D)   14	2500   LARGE T&R	Yes	NIPDAU   SN	Level-1-260C-UNLIM	-55 to 125	HC243M
CD74HC243M96.A	Active	Production	SOIC (D)   14	2500   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-55 to 125	HC243M
<a href="#">CD74HC243M96G4</a>	Active	Production	SOIC (D)   14	2500   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-55 to 125	HC243M
CD74HC243M96G4.A	Active	Production	SOIC (D)   14	2500   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-55 to 125	HC243M
<a href="#">CD74HCT243E</a>	Active	Production	PDIP (N)   14	25   TUBE	Yes	NIPDAU	N/A for Pkg Type	-55 to 125	CD74HCT243E
CD74HCT243E.A	Active	Production	PDIP (N)   14	25   TUBE	Yes	NIPDAU	N/A for Pkg Type	-55 to 125	CD74HCT243E
<a href="#">CD74HCT243M</a>	Active	Production	SOIC (D)   14	50   TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-55 to 125	HCT243M
CD74HCT243M.A	Active	Production	SOIC (D)   14	50   TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-55 to 125	HCT243M

(1) **Status:** For more details on status, see our [product life cycle](#).

(2) **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

(3) **RoHS values:** Yes, No, RoHS Exempt. See the [TI RoHS Statement](#) for additional information and value definition.

(4) **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

<sup>(5)</sup> **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

<sup>(6)</sup> **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

**OTHER QUALIFIED VERSIONS OF CD54HC243, CD74HC243 :**

- Catalog : [CD74HC243](#)
- Military : [CD54HC243](#)

NOTE: Qualified Version Definitions:

- Catalog - TI's standard catalog product
- Military - QML certified for Military and Defense Applications

**TAPE AND REEL INFORMATION**

**QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE**


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
CD74HC243M96	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
CD74HC243M96	SOIC	D	14	2500	330.0	16.4	6.6	9.3	2.1	8.0	16.0	Q1
CD74HC243M96G4	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1

**TAPE AND REEL BOX DIMENSIONS**


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
CD74HC243M96	SOIC	D	14	2500	353.0	353.0	32.0
CD74HC243M96	SOIC	D	14	2500	366.0	364.0	50.0
CD74HC243M96G4	SOIC	D	14	2500	353.0	353.0	32.0

**TUBE**


\*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (μm)	B (mm)
CD74HC243E	N	PDIP	14	25	506	13.97	11230	4.32
CD74HC243E	N	PDIP	14	25	506	13.97	11230	4.32
CD74HC243E.A	N	PDIP	14	25	506	13.97	11230	4.32
CD74HC243E.A	N	PDIP	14	25	506	13.97	11230	4.32
CD74HC243EE4	N	PDIP	14	25	506	13.97	11230	4.32
CD74HC243EE4	N	PDIP	14	25	506	13.97	11230	4.32
CD74HCT243E	N	PDIP	14	25	506	13.97	11230	4.32
CD74HCT243E	N	PDIP	14	25	506	13.97	11230	4.32
CD74HCT243E.A	N	PDIP	14	25	506	13.97	11230	4.32
CD74HCT243E.A	N	PDIP	14	25	506	13.97	11230	4.32
CD74HCT243M	D	SOIC	14	50	506.6	8	3940	4.32
CD74HCT243M.A	D	SOIC	14	50	506.6	8	3940	4.32

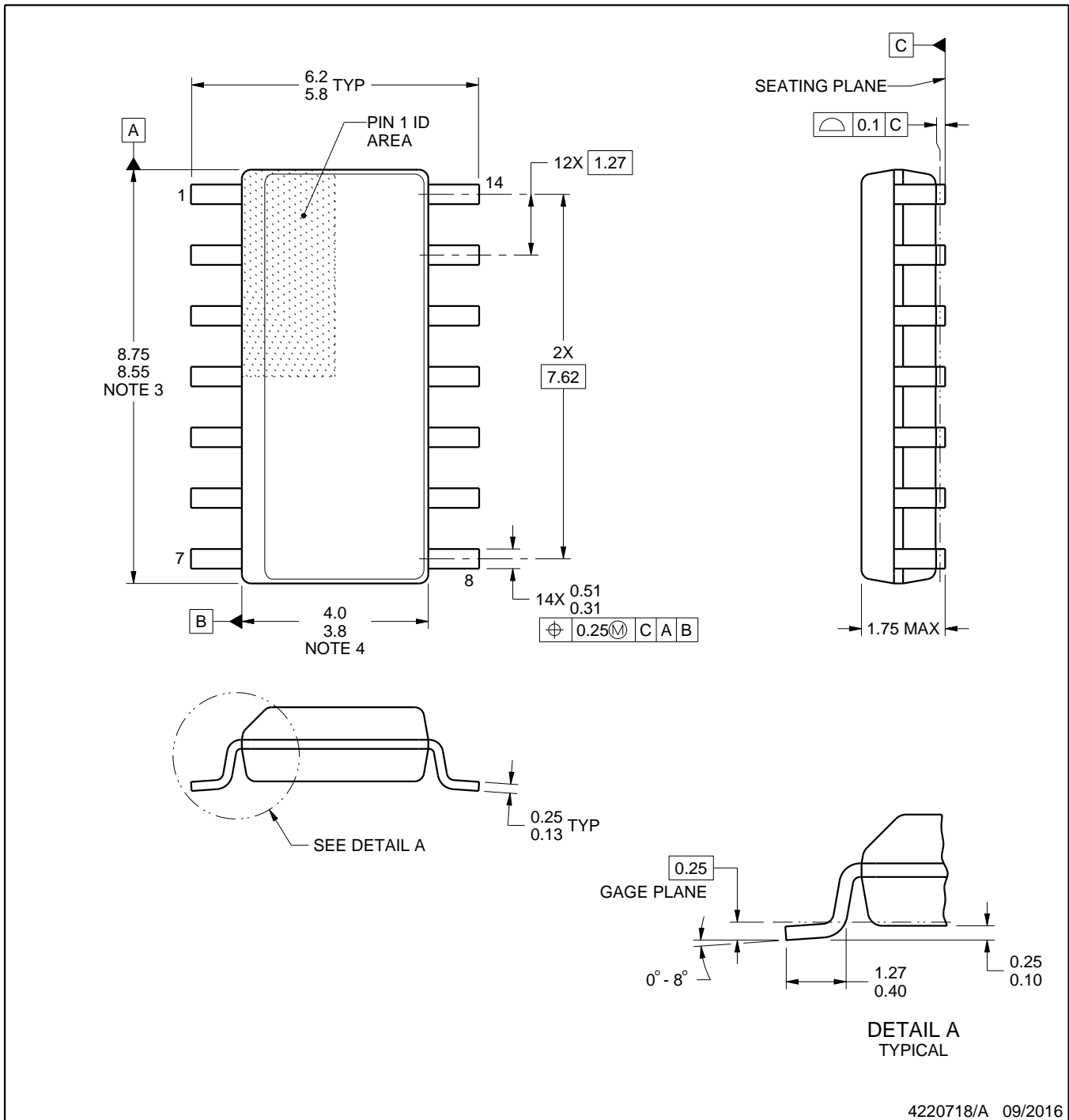
D0014A



# PACKAGE OUTLINE

## SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT



NOTES:

1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm, per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.43 mm, per side.
5. Reference JEDEC registration MS-012, variation AB.

# EXAMPLE BOARD LAYOUT

D0014A

SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT



LAND PATTERN EXAMPLE  
SCALE:8X



SOLDER MASK DETAILS

4220718/A 09/2016

NOTES: (continued)

- 6. Publication IPC-7351 may have alternate designs.
- 7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

# EXAMPLE STENCIL DESIGN

D0014A

SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT



SOLDER PASTE EXAMPLE  
BASED ON 0.125 mm THICK STENCIL  
SCALE:8X

4220718/A 09/2016

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

J 14

**GENERIC PACKAGE VIEW**  
**CDIP - 5.08 mm max height**  
CERAMIC DUAL IN LINE PACKAGE



Images above are just a representation of the package family, actual package may vary.  
Refer to the product data sheet for package details.

4040083-5/G

J0014A



# PACKAGE OUTLINE

CDIP - 5.08 mm max height

CERAMIC DUAL IN LINE PACKAGE



4214771/A 05/2017

**NOTES:**

1. All controlling linear dimensions are in inches. Dimensions in brackets are in millimeters. Any dimension in brackets or parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This package is hermetically sealed with a ceramic lid using glass frit.
4. Index point is provided on cap for terminal identification only and on press ceramic glass frit seal only.
5. Falls within MIL-STD-1835 and GDIP1-T14.

# EXAMPLE BOARD LAYOUT

J0014A

CDIP - 5.08 mm max height

CERAMIC DUAL IN LINE PACKAGE



LAND PATTERN EXAMPLE  
NON-SOLDER MASK DEFINED  
SCALE: 5X



4214771/A 05/2017



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